

## SLOVENSKI STANDARD SIST EN 62680-1-2:2018

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Nadomešča:

SIST EN 62680-1-2:2017

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Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2017)

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ICS:

35.200 Vmesniška in povezovalna Interface and interconnection

oprema equipment

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EUROPÄISCHE NORM

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#### **English Version**

### Universal serial bus interfaces for data and power - Part 1-2: Common components - USB Power Delivery specification (IEC 62680-1-2:2017)

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#### EN 62680-1-2:2017

#### **European foreword**

The text of document 100/2820/CDV, future edition 2 of IEC 62680-1-2, prepared by Technical Area 14 "Interfaces and methods of measurement for personal computing equipment" of IEC/TC 100 "Audio, video and multimedia systems and equipment" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62680-1-2:2017.

The following dates are fixed:

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# INTERNATIONAL STANDARD



Universal serial bus interfaces for data and power-VIEW
Part 1-2: Common components – USB Power Delivery specification

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#### Part 1-2: Common components - USB Power Delivery specification

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International Standard IEC 62680-1-2 has been prepared by technical area 14: Interfaces and methods of measurement for personal computing equipment, of IEC technical committee 100: Audio, video and multimedia systems and equipment.

This second edition cancels and replaces the first edition published in 2016 and constitutes a technical revision.

The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it

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The text of this standard is based on the following documents:

CDV	Report on voting
100/2820/CDV	100/2906/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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#### INTRODUCTION

The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.0a and ECNs as of 2 August 2016.

The USB Implementers Forum, Inc.(USB-IF) is a non-profit corporation founded by the group of companies that developed the Universal Serial Bus specification. The USB-IF was formed to provide a support organization and forum for the advancement and adoption of Universal Serial Bus technology. The Forum facilitates the development of high-quality compatible USB peripherals (devices), and promotes the benefits of USB and the quality of products that have passed compliance testing.

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# Universal Serial Bus Power Delivery Specification

Revision 3.0, V1.0a. 25 March 2016 + ECNs 2 August 2016

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